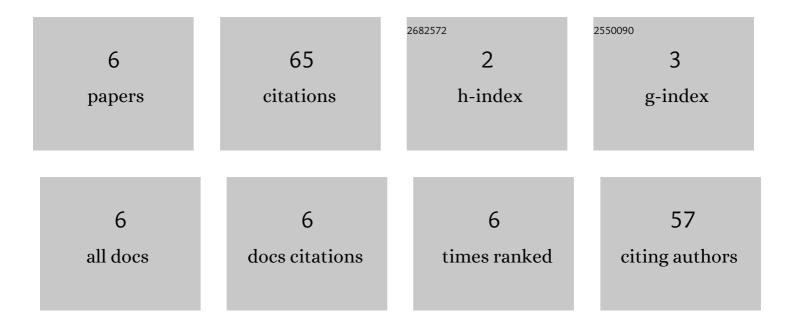
## **Biancun Xie**

List of Publications by Year in descending order

Source: https://exaly.com/author-pdf/11177857/publications.pdf Version: 2024-02-01



RIANCUN XIE

#	Article	IF	CITATIONS
1	Coupling analysis of through-silicon via (TSV) arrays in silicon interposers for 3D systems. , 2011, , .		23
2	Electrical–thermal modeling of throughâ€silicon via (TSV) arrays in interposer. International Journal of Numerical Modelling: Electronic Networks, Devices and Fields, 2013, 26, 545-559.	1.9	13
3	Electromagnetic modeling of non-uniform through-silicon via (TSV) interconnections. , 2012, , .		11
4	FDFD Modeling of Signal Paths With TSVs in Silicon Interposer. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 708-717.	2.5	10
5	Modeling and analysis of SSN in silicon and glass interposers for 3D systems. , 2012, , .		7
6	FDFD Nonconformal Domain Decomposition Method for the Electromagnetic Modeling of Interconnections in Silicon Interposer. IEEE Transactions on Electromagnetic Compatibility, 2015, 57, 496-504.	2.2	1